

Quarterly Reliability Monitoring Results

Quarters: Q1/2021 to Q4/2021

Based on structural similarity

Supplier Nexperia B.V. Name of Laboratory		User Part Number PMEG3002AELD Part Description												
										Nexperia DHAM	Schottky			
								Assembly reliability labs		MCD package				
Based on AEC-Q101 Test		Test Conditions	Duration	# Lots	# Quantity	# Rejects								
	TEST													
	Pre- and Post-Stress													
# E1	Electrical Test	Tamb = 25 °C	N/A	see below	all parts	see below								
		JESD22-A113												
		Bake Tamb = 125 °C	24 hours											
	PC	Soak Tamb = 85 °C, RH = 85%	168 hours			_								
# A1	Preconditioning	Reflow soldering	3 cycles	113	9040	0								
		MIL-STD-750-1 M1038 Method A												
	HTRB	Tj = Tjmax, Vr = 100% of max. datasheet												
. D1	High Temperature Reverse Bias	reverse voltage ^[1]	1000	116	0200	0								
# B1	Dids	reverse voitage	1000 hours	116	9280	0								
	тс	JESD22-A104												
# A4	Temperature Cycling	-65 °C to Timax, not to exceed 150°C	1000 cycles	28	2240	0								
- A-I		IESD22-A102	1000 Cycles	20	2240	0								
	AC	Tamb = 121 °C, RH = 100 %												
# A3 alt	Autoclave	Pressure = 205 kPa (29.7 psia)	96 hours	28	2240	0								
7.5 0.0		· · ·	30 110013	20	22.10									
	нзткв	JESD22-A101												
	High Humidity High	Tamb = 85 °C, RH = 85%, VR = 80 % of												
# A2 alt	Temperature Reverse Bias	rated reverse voltage ^{[1], [2]}	1000 hours	28	2240	0								
		MIL-STD-750 Method 1037												
	IOL	ton = toff, devices powered to insure ΔTj =												
# A5	Intermittent Operating Life	100 °C for 15000 cycles	1000 hours	29	2320	0								
	RSH	JESD22-A111												
# C8	Resistance to Solder Heat	260 °C ± 5 °C	10 s	n.a.	n.a.	n.a.								
	SD													
# C10	Solderability	J-STD-002		63	630	0								

^[1] The physical limitations of Schottky diodes have to be considered (thermal runaway).

Calculation of FIT and MTTF

Test considered for FIT calculation: High Temperature Reverse Bias (HTRB, Test #B1) Confidence level 60%, derated to 55 °C, activation energy 0.7 eV, test time 168 to 1000 hours

Wafer Fab	Technology	Quantity	Rejects	Failure Rate (FIT)	MTTF (hrs)
Nexperia					
DHAM	Schottky	9280	0	0.46	2.19E+09

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^[2] The maximum applied voltage is limited by test chamber set up and does not exceed 115V.